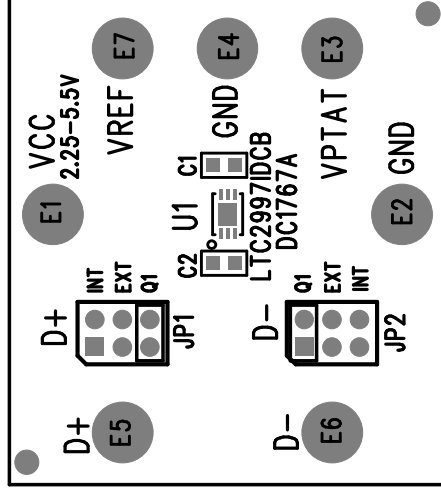


# REVISION HISTORY

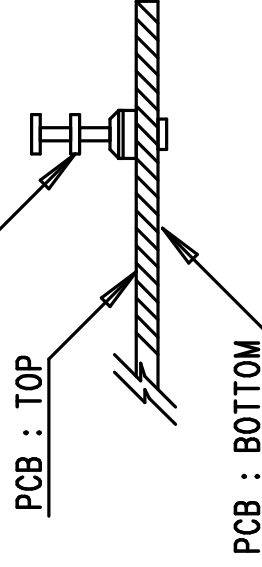
ECO	REV	DESCRIPTION	APPR	DATE
—	1	1ST PROTOTYPE	VLADIMIR O.	11-19-10

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



TURRETS : MILL-MAX 2501-2



## APPROVALS

PCB DES.	MH
APP ENG.	VLADIMIR O.
SCALE =	NONE

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TITLE: TOP ASSEMBLY DRAWING

REMOTE/INTERNAL TEMPERATURE  
SENSOR

SIZE	IC NO. LTC2997IDCB	REV.
N/A	DEMO CIRCUIT 1767A	1
FILENAME:	DC1767A-1.PCB	SHT 1 OF 2